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| <b><u>Title:</u></b>               | <i>Advanced Backside Circuit Modification (FIB Circuit Edit)</i>  |
| <b><u>Training duration:</u></b>   | <i>5 days</i>   |
| <b><u>Training cost:</u></b>       | <i>Groups of 1 – 3 trainees, US\$6000 per group</i>   |
| <b><u>Background required:</u></b> | <i>Basic Backside Circuit Modification training, or equivalent knowledge</i>  |
| <b><u>Student Objective:</u></b>   | <i>Gain ability to independently perform precision backside sample navigation, local Si thinning with various endpoint techniques, cut and connection on backside packaged device, High Aspect Ratio probe points, copper processes</i> |
| <b><u>Equipment:</u></b>           | <i>Micrion 986FC, Vectra 986(+), VectraVision</i>   |
| <b><u>Syllabus:</u></b>            | <i>Available at <a href="http://www.partbeamsystech.com/training.html">www.partbeamsystech.com/training.html</a></i>  |